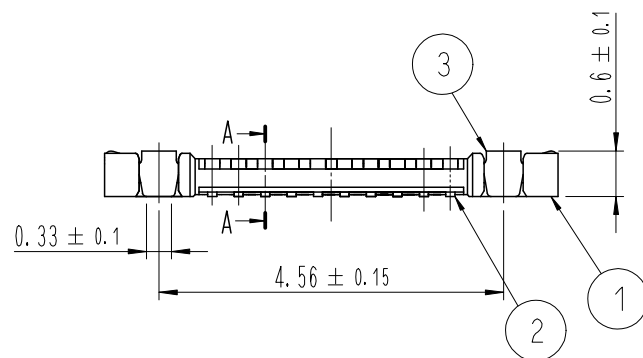
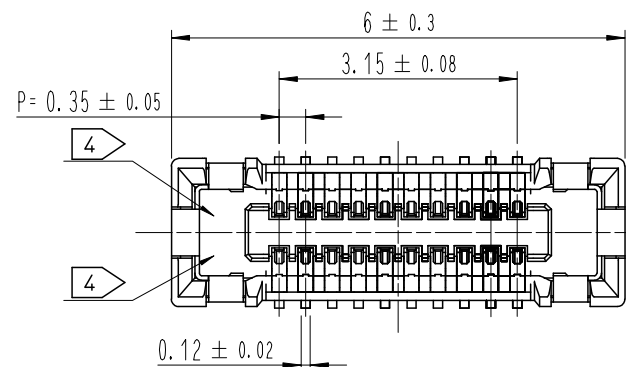


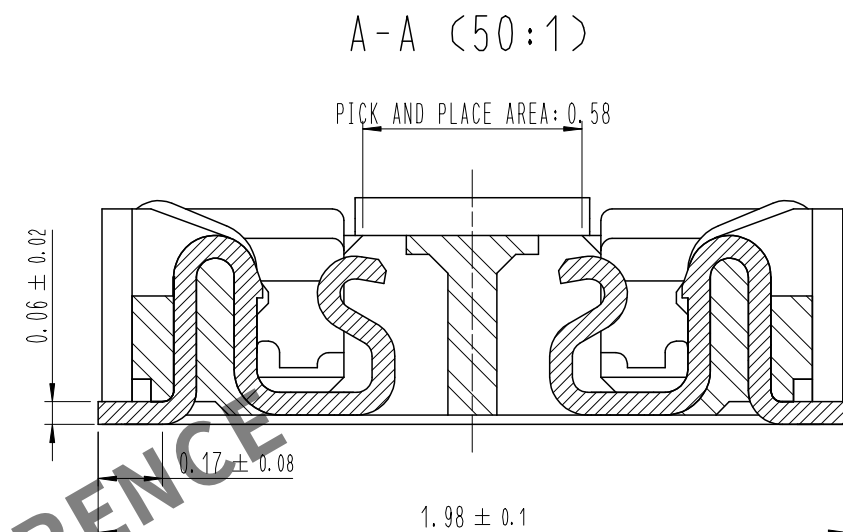
	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
△						.	△						.
△						.	△						.
△						.	△						.



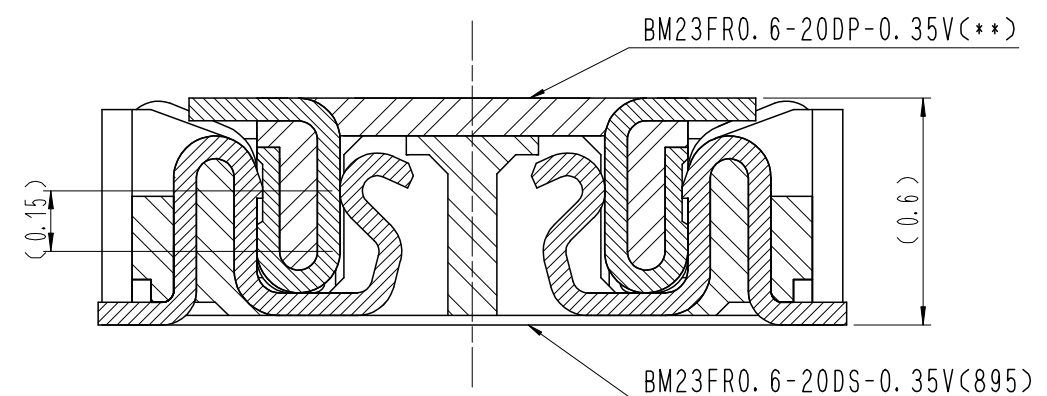
DRAWING FOR REFERENCE
This is subject to change without notice

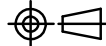
NOTE

- 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
- 2 . CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
- 3 . METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
- 4 . HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

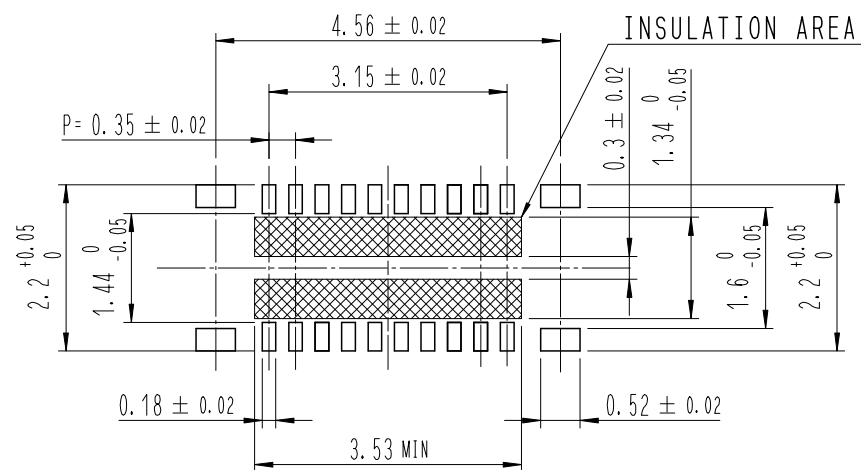


ENGAGEMENT FIGURE (50:1)

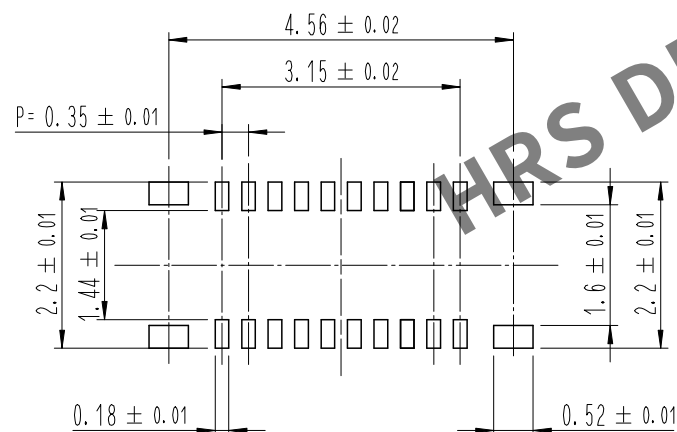


4	PS	CLEAR (EMBOSSED CARRIER TAPE)						
3	COPPER ALLOY	③	7	PS	CLEAR (REINFORCEMENT COLLAR)			
2	COPPER ALLOY	②	6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS			
REMARKS				DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
				S. H. JUNG 17. 05. 08	S. H. JUNG 17. 05. 08	H. W. JO 17. 05. 08	T. S. KANG 17. 05. 08	17. 05. 08
CODE NO. (COLD)		DRAWING NO.	PART NO.					
	SCALE	EDC3-631851	BM23FR0. 6-20DS-0. 35V(895)					
	10:1							
	UNITS	 HIROSE KOREA CO., LTD.	CODE NO					1 / 3
	mm		CL 6644-0010-8-895					

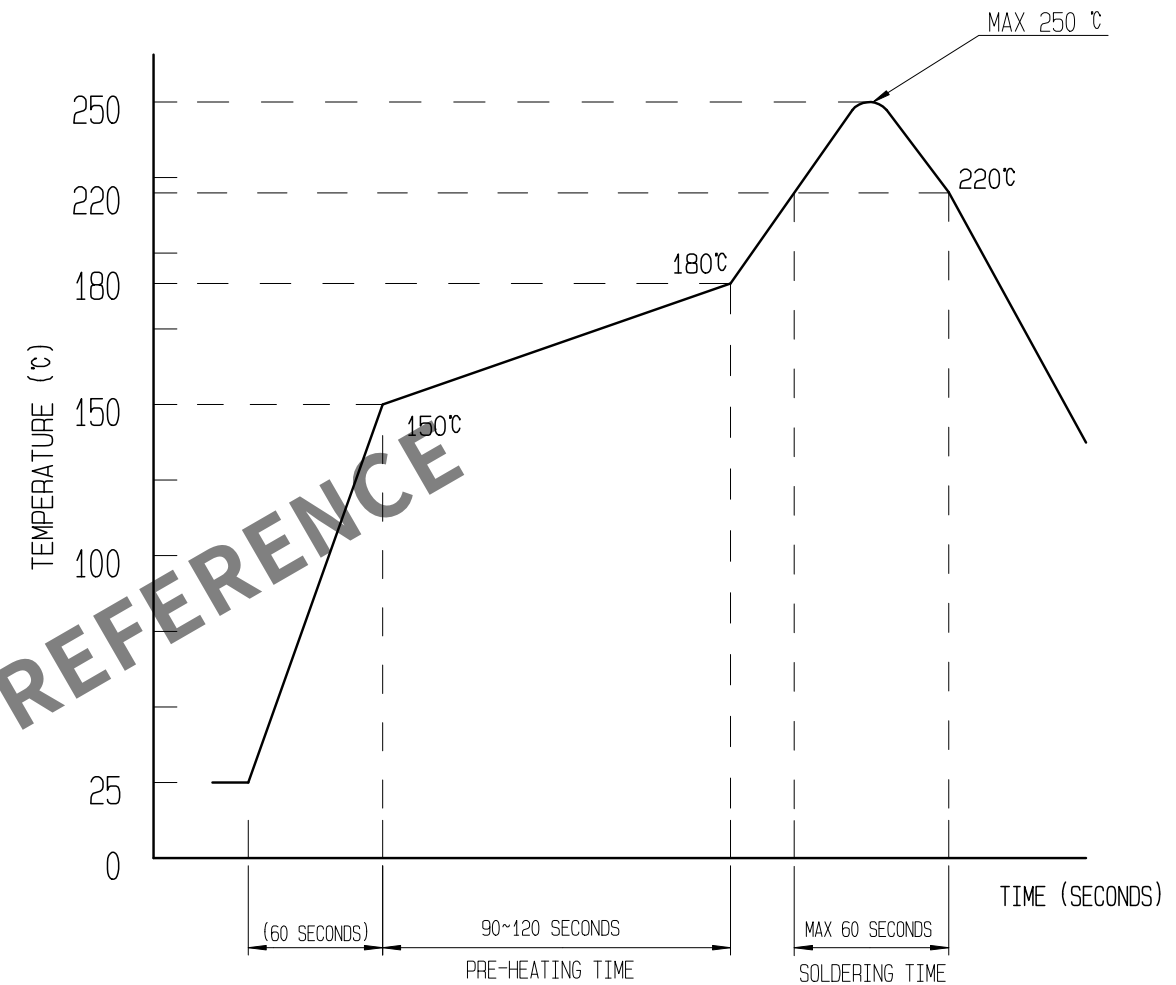
6 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS
MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.

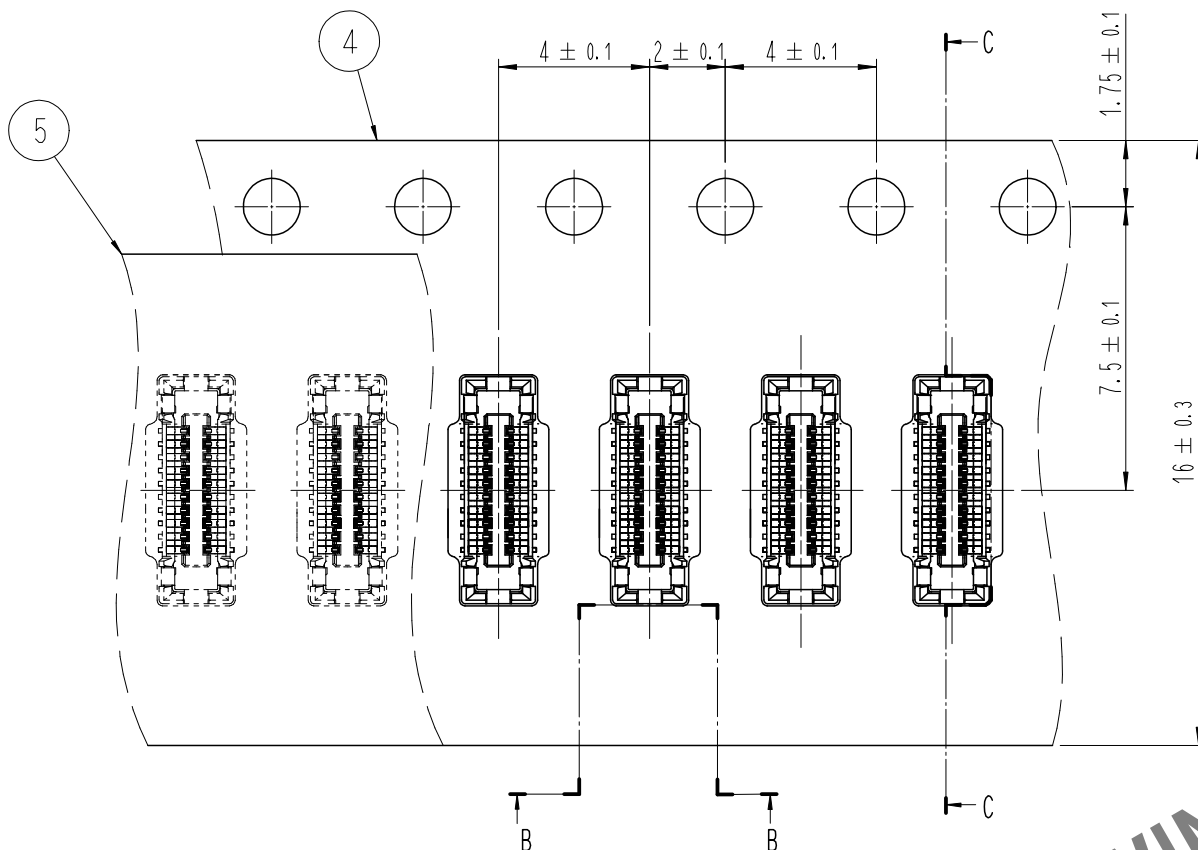


REFLOW METHOD: N2 REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150°C
PRE-HEAT TEMPERATURE (MAX): 180°C
PRE-HEAT TIME: 90~120 SEC.

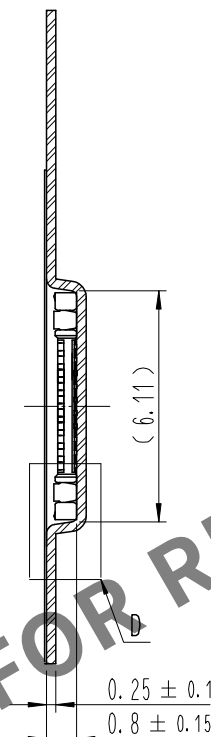
5. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-631851	PART NO.	BM23FR0.6-20DS-0.35V(895)
	SCALE	10:1	CODE NO	CL 6644-0010-8-895
	UNITS	mm		

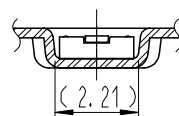
EMBOSSSED CARRIER TAPE PACKAGING (5:1)



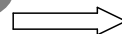
C-C (5:1)



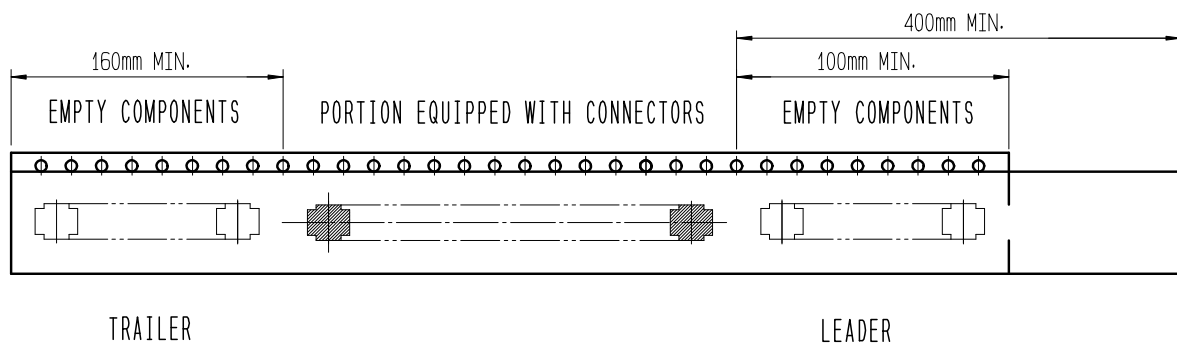
B-B (5:1)



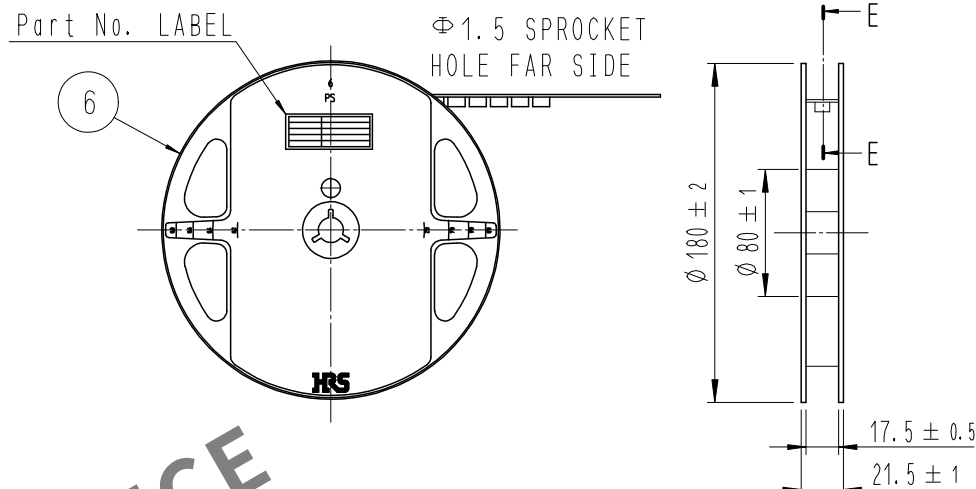
DIRECTION OF UNREELING



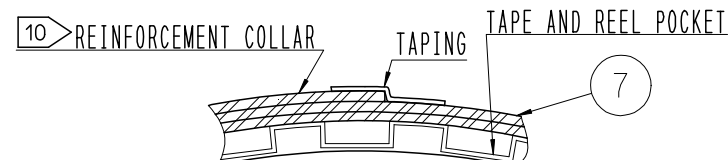
9 TAPING(FREE)



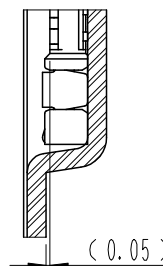
STYLE AND DIMENTION OF REEL (FREE)



F-F (FREE)



D (10:1)



DETAIL OF PART No. LABEL

SUPPLIER	
QUANTITY	
PART NO.	
CODE NO.	
DATE OF MANUFACTURED	
生産月日	年 月 日
図番	** ** *
品名	BM23FR0.6-20DS-0.35V(895)
納入数量	1,000個
納入者	HIROSE KOREA

7 . PER REEL 1,000 CONNECTORS.

8 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

9 REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

10 AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

	DRAWING NO. EDC3-631851		PART NO. BM23FR0.6-20DS-0.35V(895)	
	SCALE 10:1 UNITS mm		CODE NO CL 6644-0010-8-895	
 HIROSE KOREA CO., LTD.			3 2	